

PCN # 165
Notification Date:
16 April 2018

Product / Process Change Notice

Parts Affected:

Chip process CP206, N-Channel Field Effect Transistors, wafers, and bare die.

Extent of Change:

The CP206 wafer process has been discontinued and replaced with the CP216 wafer process. See figures 1 and 2 for details.

Reason for Change:

This process was transferred to an alternate wafer foundry which provides improved and consistent yields.

Effect of Change:

The wafer process meets all electrical specifications of the individual devices listed on the following page.

Qualification:

Test	Condition	Failure rate
Resistance to Solder Shock	T = 260°C ± 5°C Dwell time = 10 sec. JESD22-B106	0/77
High Temperature Storage Life/ bake test.	150°C (-0/+10)°C, 1000 hours. JESD22-A103	0/77
Temperature Cycling	T = -65°C to +150°C 1000 cycles. Dwell time = 15 min. JESD22-A104	0/77
High Temperature Reverse Bias (HTRB)	T = 125°C, t = 1000 hours, V _R = V _Z JESD22-A108	0/77
Highly Accelerated Temperature and Humidity Stress Test (HAST)	T = 130°C, RH = 85%, P = 33.3 psia, and t = 96 hours. Bias conditions per device specification sheet. JESD22-A110	0/77
Accelerated Moisture Resistance Unbiased Autoclave	Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 29.7 psia (15psig). t = 96 hours JESD22-A102	0/77

Effective Date of Change:

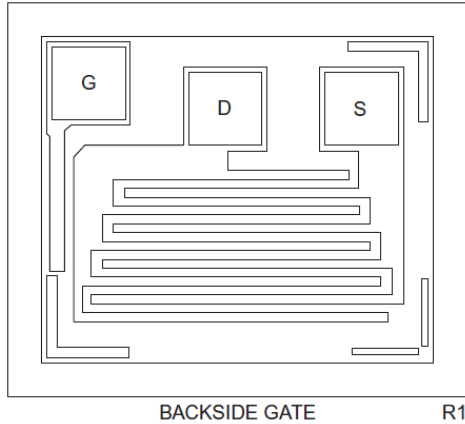
April 16, 2018 - Existing inventory will be shipped until depleted.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

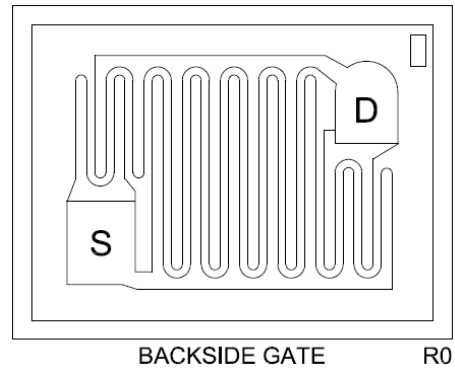
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Figure 1: CP206 Chip Geometry (Discontinued)



Wafer Diameter: 5 inch
Die Size: 21 x 18 mils
Die Thickness: 8.0 mils
Bond Pad Size (Drain): 3.0 x 3.0 mils
Bond Pad Size (Source): 3.0 x 3.0 mils
Bond Pad Size (Gate): 3.0 x 3.0 mils
Topside Metal: Al (30,000Å)
Backside Metal: Au (6,000Å)

Figure 2: CP216 Chip Geometry



Wafer Diameter: 4 inch
Die Size: 21 x 16 mils
Die Thickness: 7.9 mils
Bond Pad Size (Drain): 3.3 x 4.5 mils
Bond Pad Size (Source): 3.3 x 4.5 mils
Topside Metal: Al (10,000Å)
Backside Metal: Au (3,250Å)

Part Numbers Affected:

2N4391	CP206-2N4391-CT
2N4392	CP206-2N4391-WN
2N4393	CP206-2N4392-CM
2N4092	CP206-2N4392-CT
2N4861	CP206-2N4392-WN
2N4861A	CP206-2N4393-CT
CMPF4391	CP206-2N4393-WN
CMPF4392	
CMPF4393	



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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	